

ABSTRACT OF THE DISCLOSURE

A die used for molding an electronic component with resin includes a fixed, top die and a movable, bottom die and at least has a surface contacting a melted resin material that is electroplated with nickel-tungsten alloy.

- 5 This plating can provide releaseability of a resin-molded body and the like superior to hard-chromium plating to allow an ejector pin to efficiently eject and release the resin-molded body from the die.

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